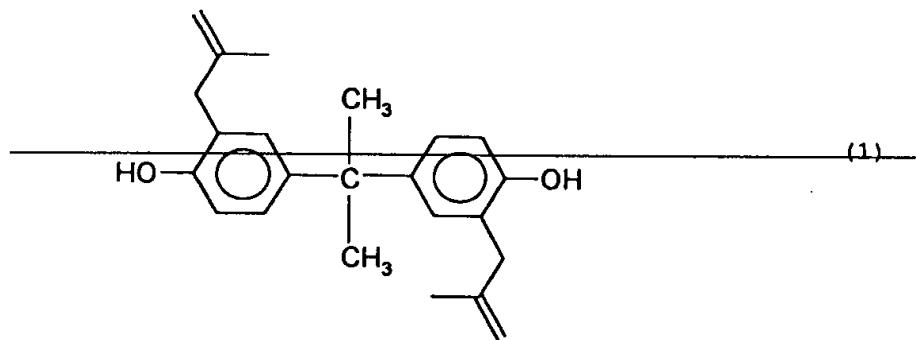


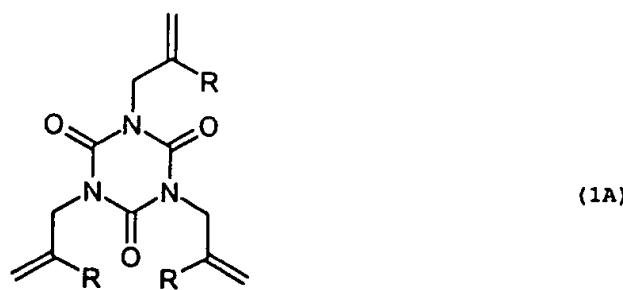
**AMENDMENTS TO THE CLAIMS:**

1. (Currently Amended) A laminated board comprising a prepreg sheet or prepreg sheets prepared by impregnating a reinforcing fiber material with the thermosetting low-dielectric resin composition comprising a component (a): siloxane-modified polyimide, component (b): ~~a compound containing 2 methylallyl groups and having the following formula (1) or a compound containing 3 allyl groups or 3 methylallyl groups and having the following formula (1A)~~ or a compound containing 3 allyl groups or 3 methylallyl groups and having the following formula (1A), and component (c): a compound containing at least 2 maleimide groups.

Formula (1):



Formula (1A):



wherein R is a hydrogen atom or methyl group.

2. (Original ) The laminated board according to claim 1, wherein the laminated board is a metal-clad laminate formed of the laminated board and a metal foil or foils which is or are stacked on and integrated with one surface or both surfaces of the laminated board.

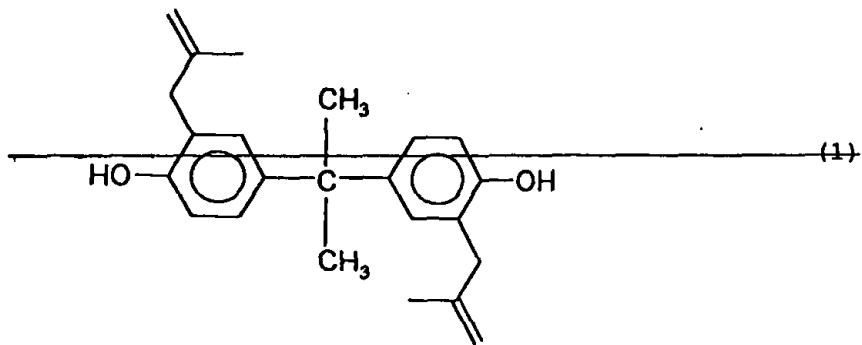
3. (Original ) The laminated board according to claim 2, wherein the metal-clad laminate is formed of a sheet or sheets of a prepreg impregnated with the thermosetting low-dielectric resin composition in a semi-cured state or a cured state and a metal foil or metal foils is/are laminated on and integrated with the prepreg.

4. (Original ) The laminated board according to claim 1, wherein the reinforcing fiber material is a fabric or a non-woven fabric formed of at least one member selected from the group consisting of an aramid fiber, an aromatic polyester fiber and a tetrafluorocarbon fiber.

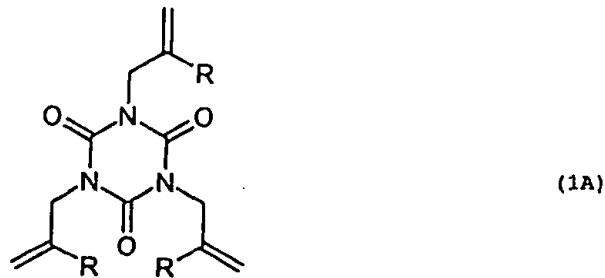
5. (Currently Amended) The laminated board according to claim 1, wherein the metal foil is a metal foil formed of at least one member selected from the group consisting of copper, cupronickel, silver, iron, ~~42~~ Ni/Fe alloy and stainless steel.

6. (Currently Amended) A circuit laminate material comprising either a peeling-off layer or a metal foil and the thermosetting low-dielectric resin composition comprising a component (a): siloxane-modified polyimide, component (b): ~~a compound containing 2 methylallyl groups and having the following formula (1) or a compound containing 3 allyl groups or 3 methylallyl groups and having the following formula (1A)~~, and component (c): a compound containing at least 2 maleimide ~~groups~~ groups:

Formula (1):



Formula (1A):

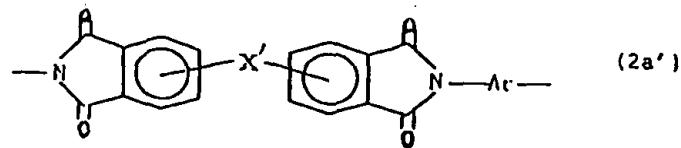


wherein R is a hydrogen atom or methyl group, which thermosetting low-dielectric resin composition is an adhesive layer laminated one surface of the peeling-off layer or the metal foil.

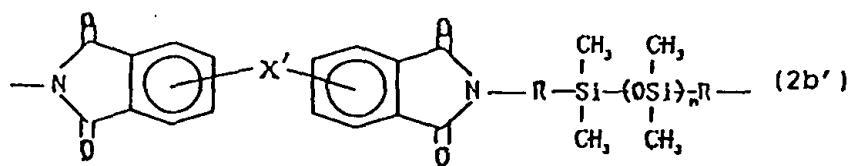
*Claim 7 (Cancelled)*

8. (Currently Amended) The circuit laminate material according to claim 6, wherein the siloxane-modified polyimide as a component (a) contains 90 to 40 mol% of at least one of structural units of the following formula (2a') and 10 to 60 mol% of structural units of the following formula (2b') when the component (b) has the formula (1A).

Formula (2a')

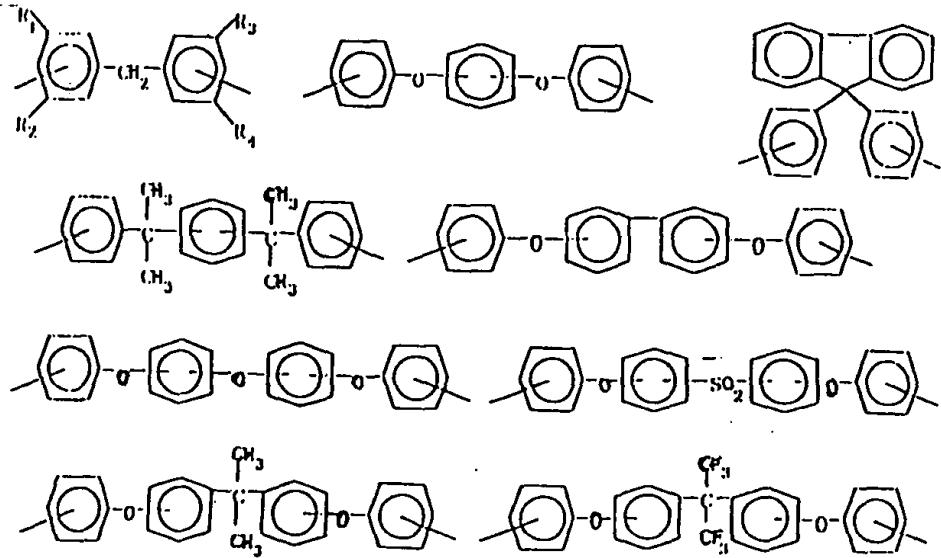


Formula (2b')



wherein X is a direct bond or any one of binding groups of -O-, -SO<sub>2</sub>-, -CO-, -C(CH<sub>3</sub>)<sub>2</sub>-, -C(CF<sub>3</sub>)<sub>2</sub>- and -COOCH<sub>2</sub>CH<sub>2</sub>OCO-, Ar is a divalent group selected from aromatic-ring-possessing groups of the following formula (3A), R is -CH<sub>2</sub>OC<sub>6</sub>H<sub>4</sub>- whose methylene group is bonded to Si or an alkylene group having 1 to 10 carbon atoms, and n is an integer of 1 to 20,

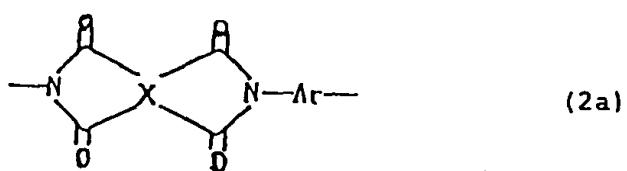
Formula (3A):



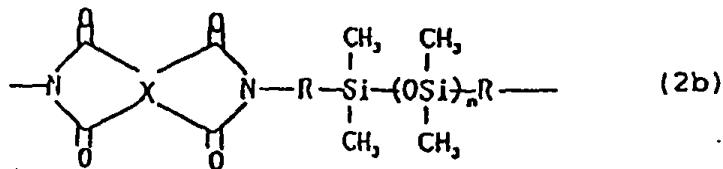
wherein each of R<sub>1</sub>, R<sub>2</sub>, R<sub>3</sub> and R<sub>4</sub> is independently a hydrogen atom or an alkyl or alkoxy group having 1 to 4 carbon atoms provided that all of these are hydrogen atoms in no case.

9. (Currently Amended) The circuit laminate material according to claim 6, wherein the siloxane-modified polyimide as a component (a) contains 90 to 40 mol% of at least one of structural units of the following formula (2a) and 10 to 60 mol% of structural units of the following formula (2b) ~~when the component (b) has the formula (1A)~~.

Formula (2a):



Formula (2b)

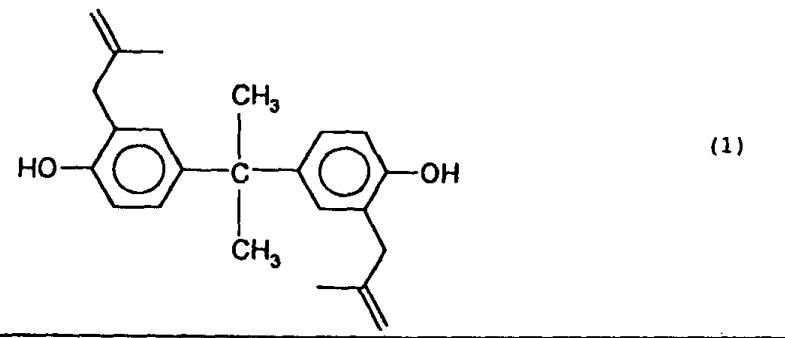


wherein X is a tetravalent aromatic group and is any one of a 3, 3', 4, 4'-diphenylsulfone structure, a 3, 3', 4, 4'-biphenyl structure and 2, 3', 3, 4'-biphenyl structure, Ar is a divalent group selected from aromatic-ring-possessing groups of the following formula (3A) recited claim 4, R is -CH<sub>2</sub>OC<sub>6</sub>H<sub>4</sub>- whose methylene group is bonded to Si or an alkylene group having 1 to 10 carbon atoms, and n is an integer of 1 to 20.

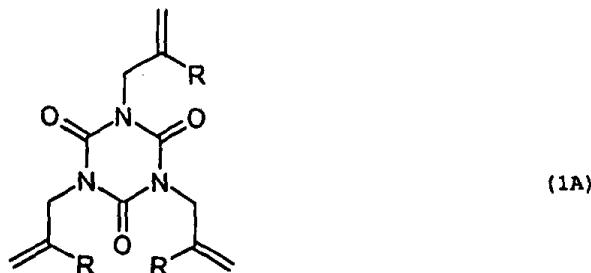
10. (Original) The circuit laminate material according to claim 6, wherein the metal foil has a thickness of 10 to 300  $\mu\text{m}$ .

11. (Currently Amended) The circuit laminate material according to claim 6 comprising either a peeling-off layer or a metal foil and the thermosetting low-dielectric resin composition comprising a component (a): siloxane-modified polyimide, component (b): a compound containing 2 methylallyl groups and having the following formula (1) or a compound containing 3 allyl groups or 3 methylallyl groups and having the following formula (1A), and component (c): a compound containing at least 2 maleimide groups:

Formula (1):



Formula (1A):

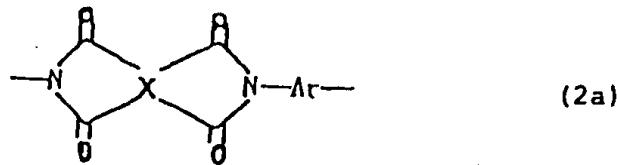


wherein R is a hydrogen atom or methyl group, which thermosetting low-dielectric resin composition is an adhesive layer laminated one surface of the peeling-off layer or the metal foil,

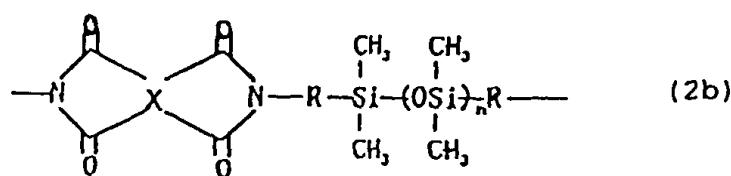
wherein the adhesive layer has a peeling-off layer formed on one surface opposite to the metal foil or the film.

12. (New) The circuit laminate material according to claim 11, wherein the siloxane-modified polyamide as a component (a) contains 90 to 40 mol% of at least one of structural units of the following formula (2a) and 10 to 60 mol% of at least one of structural units of the following formula (2b) when the component (b) is the compound of the formula (1).

Formula (2a):

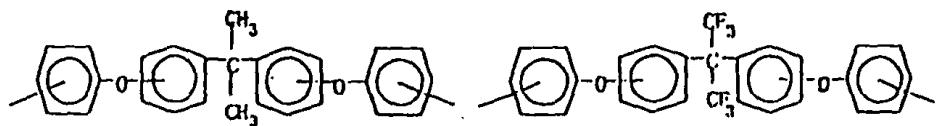
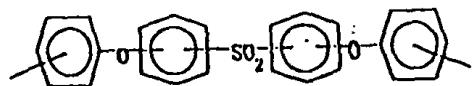
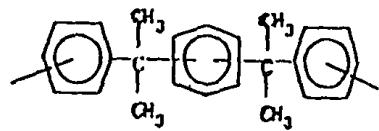
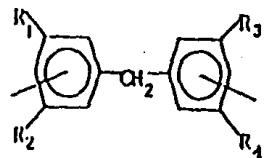


Formula (2b):



wherein X is a tetravalent aromatic group and is any one of a 3, 3', 4, 4'-diphenylsulfone structure, a 3, 3', 4, 4'-biphenyl structure and 2, 3', 3, 4'-biphenyl structure, Ar is a divalent group selected from aromatic-ring-possessing groups of the following formula (3), R is  $-\text{CH}_2\text{OC}_6\text{H}_4-$  whose methylene group is bonded to Si or an alkylene group having 1 to 10 carbon atoms, and n is an integer of 1 to 20,

Formula (3):



wherein each of R<sub>1</sub>, R<sub>2</sub>, R<sub>3</sub> and R<sub>4</sub> is independently a hydrogen atom or an alkyl or alkoxy group having 1 to 4 carbon atoms provided that all of these are hydrogen atoms in no case.